

## RESIN BOND BLADES

## 1000/1000C SERIES



### APPLICATIONS

Ceramics, glass, crystalline materials, semiconductor packages, hard materials requiring high wear characteristics

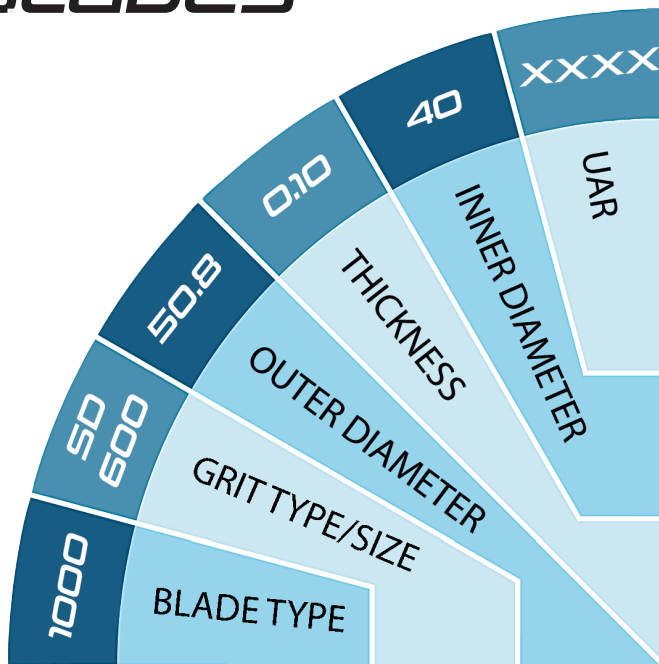
**1000 SERIES** dicing blades are used for substrates that require continued fresh exposure of diamonds to ensure free cutting. A wide variety of blade matrix options are available to optimise your cutting processes. These options include a variety of coated and uncoated diamond grit sizes, various bond strengths, a choice of resins, and various manufacturing processes that control diamond concentration and overall density.



### **1000C SERIES**

Also available are the 1000C series resin bond blades for use with dicing saws requiring a conductive blade.

# RESIN BOND BLADES



BLADE TYPE	GRIT TYPE/SIZE	OUTER DIAMETER	THICKNESS	INNER DIAMETER	UAR
1000 Resin bond, Hubless	SD- Synthetic diamond 150, 180, 220, 240, 280, 320, 400, 500, 600, 800 grit	50 - 127mm	0.070 - 2.00mm	40mm	UAR- Unique Application Reference, - unique code that incorporates a number of parameters to suit your application. *

\* Options available on bond type, concentration and additive ingredients

## Loadpoint Expertise

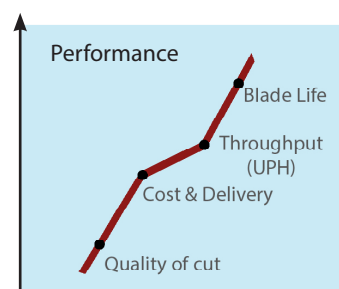
Our customers trust Loadpoint to help them develop class-leading products. We have helped many customers develop task orientated solutions for ultrasound scanners, inkjet printers, SAW filters, MEMS devices and a whole range of silicon based products.

## Loadpoint Blade Ranges

- Resin Blade
- Hubbed Blade
- Resin on steel core
- Electroformed Blade
- Metal Blade
- Vitriified Blade



## Blade Optimisation Program



Loadpoint can optimise a blade for any process based on any number of target objectives.

Let us know your dicing challenges and we will put together a program to enhance your process.

## Micromachining solutions for:

SEMICONDUCTORS	OPTICAL
ELECTRONICS	MEDICAL/ULTRASOUND
FERRO-ELECTRONICS	SOLAR
OPTO-ELECTRONICS	SONAR